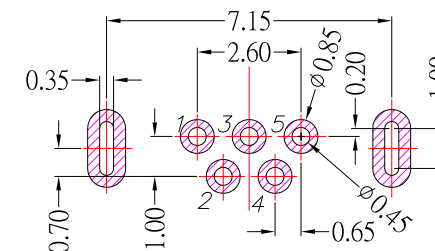
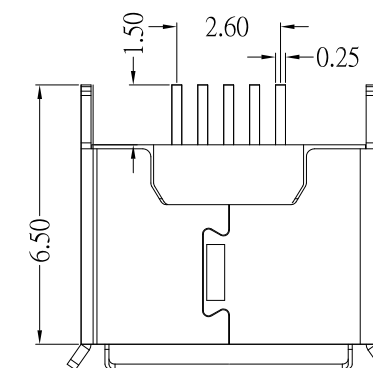
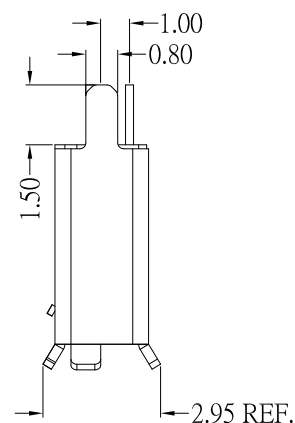
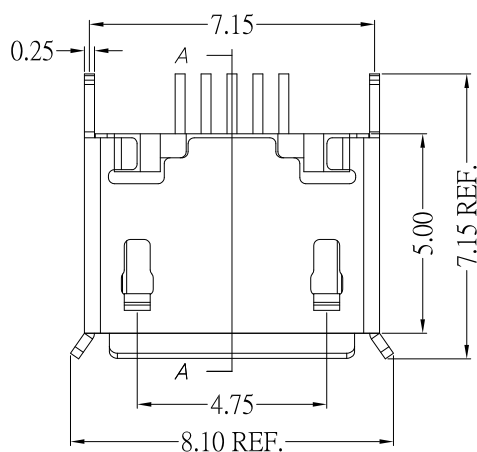


— 鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



SECTION A-A



MATERIAL:

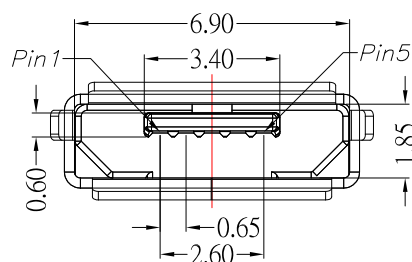
Finish:

2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 CURRENT RATING: 1.8A(PIN 1&5) MAX ; 1.0A(PIN 2&3&4) MAX
3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min
3.3 CONTACT RESISTANCE: 30 mΩ MAX.
3.4 INSULATION RESISTANCE: 100 MΩ MIN.
3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
3.7 TEMPERATURE RANGE: -30°C ~ +80°C



TOLERANCE UNLESS OTHERWISE STATED :	Up to 5	± 0.2	3RD. ANGEL'S		UNITS	MM
	Above 5 ~ 15	± 0.3				
	Above 15 ~ 30	± 0.4				
	Above 30 ~ 50	± 0.5				
	Angle	$\pm 0.3^\circ$				

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR	
Jack Lu	01/06/22					
CHECKED BY:	DATE	FINISH		MODLE	MICRO USB 5PF ABTYPE 直立式 捲邊 腳長 1.5mm	
Jacky Chen	01/06/22	SCALE	1 : 1	DWG NO.	MRUSB-5AB-V-x-S347	SIZE A4
APPROVED BY:	DATE	SHEET NO.	1 of 1	PART NO.	MRUSB-5AB-V-x-S347	VER
Tony Kao	01/06/22					R2